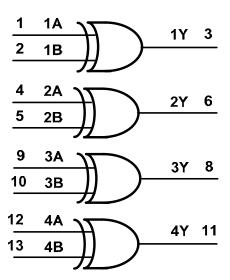


Pin Descriptions

Pin Number	Pin Name	Description
1	1A	Data Input
2	1B	Data Input
3	1Y	Data Output
4	2A	Data Input
5	2B	Data Input
6	2Y	Data Output
7	GND	Ground
8	3Y	Data Output
9	3A	Data Input
10	3B	Data Input
11	4Y	Data Output
12	4A	Data Input
13	4B	Data Input
14	V _{CC}	Supply Voltage

Logic Diagram



Function Table

Inp	Output	
Α	В	Y
L	L	L
L	Н	Н
Н	L	Н
Н	Н	L



Absolute Maximum Ratings (Note 4) (@T_A = +25°C, unless otherwise specified.)

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	KV
ESD CDM	Charged Device Model ESD Protection	1	KV
ESD MM	Machine Model ESD Protection	200	V
V _{CC}	Supply Voltage Range	-0.5 to 6.5	V
Vı	Input Voltage Range	-0.5 to 6.5	V
Vo	Voltage applied to output in high impedance or I _{OFF} state	-0.5 to 6.5	V
Vo	Voltage applied to output in high or low state	-0.3 to V _{CC} +0.5	V
lıĸ	Input Clamp Current V _I <0	-50	mA
lok	Output Clamp Current V _O <0	-50	mA
Io	Continuous output current	50	mA
I _{CC} ,, I _{GND}	Continuous current through Vcc or GND	±100	mA
TJ	T _J Operating Junction Temperature		°C
T _{STG}	T _{STG} Storage Temperature		°C
P _{TOT}	Total Power Dissipation	500	mW

Note: 4. Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.

Recommended Operating Conditions (Note 5) (@T_A = +25°C, unless otherwise specified.)

Symbol	Parameter	Conditions	Min	Max	Unit	
V _{CC}	Supply Voltage		1.65	5.50	V	
VI	Input Voltage		0	5.5	V	
	Outrot Vallage	Active Mode	0	V _{CC}	V	
Vo	Output Voltage	V _{CC} = 0V; Power Down Mode	0	5.5	V	
A . / A > /		V _{CC} = 1.65V to 2.7V		20	0.4	
Δt/ΔV	Input transition rise or fall rate	V _{CC} = 2.7V to 5.5V		10	ns/V	
T _A	Operating free-air temperature		-40	+125	°C	

Note: 5. Unused inputs should be held at V_{CC} or Ground.



Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Compleal	Dovernator	Took Conditions	v	T _A = -40°C	C to +85°C	T _A = -40°C	to +125°C	l lmi4
Symbol	Parameter	Test Conditions	V _{CC}	Min	Max	Min	Max	Unit
			1.65V to 1.95V	0.65 X V _{CC}		0.65 X V _{CC}		
.,	High-level Input		2.3V to 2.7V	1.7		1.6		V
V_{IH}	Voltage		2.7V to 3.6V	2.0		2.0		V
			4.5V to 5.5V	0.7 X V _{CC}		2.0		
			1.65V to 1.95V		0.35 X V _{CC}		0.35 X V _{CC}	
	Low-level input		2.3V to 2.7V		0.7		0.7	V
V_{IL}	voltage		2.7V to 3.6V		0.8		0.8	V
			4.5V to 5.5 V		0.3 X V _{CC}		0.3 X V _{CC}	
		I _{OH} = -100μA	1.65V to 3.6V	V _{CC} - 0.2		V _{CC} - 0.3		
		I _{OH} = -4mA	1.65V	1.2				V
	High Level Output Voltage	I _{OH} = -8mA	2.3V	1.9				
V_{OH}		104	2.7V	2.2		2.05		V
		I _{OH} = -12mA	3.0V	2.3		2.1		
		I _{OH} = -24mA	3.0V	2.2		2.0		
		I _{OH} = 100μA	1.65V to 5.5V		0.2		0.3	
		I _{OH} = 4mA	1.65V		0.45		0.6	
.,	High-level	I _{OH} = 8mA	2.3V		0.70		0.85	V
V_{OL}	Output Voltage	10	2.7V		0.40		0.6	V
		I _{OH} = 12mA	3.0V		0.55		0.6	
		I _{OH} =-24mA	3.0V		0.55		0.6	
l _l	Input Current	V _I =GND to 5.5V	3.6V		±5		±20	μA
I _{OFF}	Power Down Leakage Current	V _I or V _O = 0V to 3.6V	0		10		20	μΑ
Icc	Supply Current	V _I = GND or V _{CC} I _O =0	3.6V		10		40	μA
ΔI _{CC}	Additional Supply Current	One input at V _{CC} -0.6V Other	2.7V to 3.6V		500		5000	μΑ



Switching Characteristics

Cumbal Baramatar		Test	Test	T _A = +25°C		-40°C to +85°C		-40°C to +125°C		11:4	
Symbol	Parameter	Conditions	V _{CC}	Min	Тур	Max	Min	Max	Min	Max	Unit
	_	Propagation Delay A _N or B _N Figure 1	1.65V to1.95V	1.0	4.1	9.4	1.0	9.9	1.0	11.4	
	, ,		2.3V to 2.7V	1.0	2.9	7.1	1.0	7.6	1.0	9.7	
t _{PD}	to Y _N		2.7V	1.0	2.8	5.4	1.0	5.6	1.0	7.1	ns
	LO IN		3.0V to 3.6V	1.0	2.5	4.4	1.0	4.6	1.0	5.8	
Output Skew			2.0\/ to 2.6\/					1.0		1.5	
t _{SK(0)}	Time		3.0V to 3.6V					1.0		1.5	ns

Operating Characteristics (@T_A = +25°C, unless otherwise specified.)

	Parameter		V _{CC} = 1.8V	$V_{CC} = 2.5V$	V _{CC} = 3.3V	Unit	
	raiailletei	Conditions Typ		Тур	Тур	Onit	
C_{pd}	Power dissipation capacitance per gate	f = 10 MHz	6.4	7.4	8.4	pF	
Cı	Input Capacitance	$V_i = V_{CC} - or$ GND	4	4	4	pF	

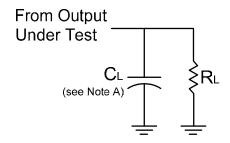
Package Characteristics

Symbol	Parameter	Test Conditions	V _{CC}	Min	Тур	Max	Unit
0	Thermal Resistance	SO-14	(Nata C)		TBD		°C/W
θ_{JA}	Junction-to-Ambient	TSSOP-14	(Note 6)		159		
0	Thermal Resistance	SO-14	(Nata C)		TBD		°C/W
θЈС	Junction-to-Case	TSSOP-14	(Note 6)		25		

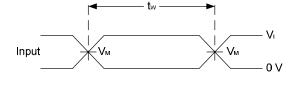
Note: 6. Test condition for SO-14 and TSSOP-14: Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.



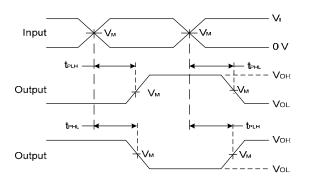
Parameter Measuement Information



V	V Inputs V		V		В	
V _{CC}	VI	t _r /t _f	V _M	C∟	R_L	
1.8V±0.15V	V _{CC}	≤2ns	V _{CC} /2	30pF	1ΚΩ	
2.5V±0.2V	V _{CC}	≤2ns	V _{CC} /2	30pF	500Ω	
2.7V	2.7V	≤2.5ns	1.5V	50pF	500Ω	
3.3V±0.3V	2.7V	≤2.5ns	1.5V	50pF	500Ω	



Voltage Waveform Pulse Duration



Voltage Waveform Propagation Delay Times Inverting and Non Inverting Outputs

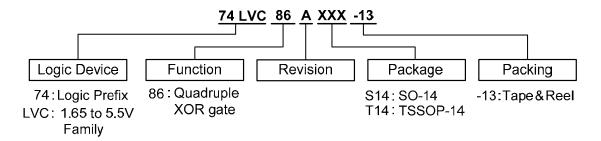
Notes: A . Includes test lead and test apparatus capacitance.

- B. All pulses are supplied at pulse repetition rate ≤ 10 MHz
 C. Inputs are measured separately one transition per measurement
- D. t_{PLH} and t_{PHL} are the same as t_{PD}

Figure 1. Load Circuit and Voltage Waveforms



Ordering Information

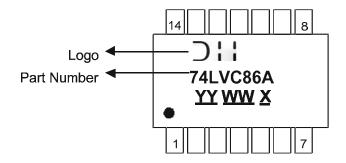


	Device	Package	Packaging	13" Tape and Reel		
	Device	Code	(Note 7)	Quantity	Part Number Suffix	
Po	74LVC86AS14-13	S14	SO-14	2500/Tape & Reel	-13	
Pb	74LVC86AT14-13	T14	TSSOP-14	2500/Tape & Reel	-13	

Notes: 7. The taping orientation and tape details can be found at http://www.diodes.com/datasheets/ap02007.pdf

Marking Information

(1) SO-14, TSSOP-14



<u>YY</u>: Year: 08, 09,10~ <u>WW</u>: Week: 01~52; 52 represents 52 and 53 week

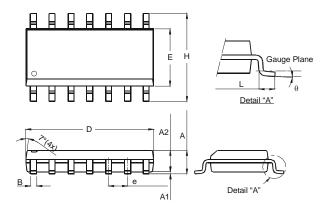
X : Internal Code

Part Number	Package
74LVC86AS14	SO-14
74LVC86AT14	TSSOP-14



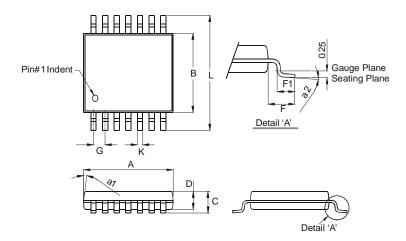
Package Outline Dimensions (All dimensions in mm.)

Package Type: SO-14



SO-14						
Dim	Min	Max				
Α	1.47	1.73				
A1	0.10	0.25				
A2	1.45	Тур				
В	0.33	0.51				
D	8.53	8.74				
Е	3.80	3.99				
е	1.27	Тур				
Н	5.80	6.20				
L	0.38	1.27				
θ	0°	8°				
All Dimensions in mm						

Package Type: TSSOP-14

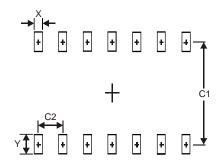


TSSOP-14			
Dim	Min	Max	
a1	7° (4X)		
a2	0°	8°	
Α	4.9	5.10	
В	4.30	4.50	
С	_	1.2	
D	0.8	1.05	
F	1.00 Typ		
F1	0.45	0.75	
G	0.65 Typ		
K	0.19	0.30	
L	6.40 Typ		
All Dimensions in mm			



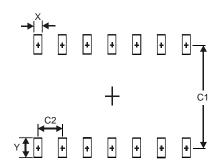
Suggested Pad Layout

Package Type: SO-14



Dimensions	Value (in mm)	
Х	0.60	
Υ	1.50	
C1	5.4	
C2	1 27	

Package Type: TSSOP-14



Dimensions	Value (in mm)	
Х	0.45	
Y	1.45	
C1	5.9	
C2	0.65	



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